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#### Vision based Platforms

Kees Vissers, mpsoc 2016



#### Agenda

Vision processing
Autonomous Driving
Roofline model
Energy and size
Xilinx solutions



# **Vision Processing**



#### Computer Vision: pedestrians and obstacles.



Active obstacle detection and avoidance

Drone autonomously avoid obstacles

Milliseconds, versus seconds response time, no time to go to the cloud

# Analysis: Image Database, Transform and Classification



3D reconstruction from drone images



Find photos by what's in them Looking for that photo of your pup? Just tap "dog" or the place you took it to find it faster.

#### Image Classification

# (Embedded) Visualization: Smart/Augmented Views



Smart Rearview Mirror



Multiple cameras



#### Smart Augmented Wide View



#### **Computer Vision/Visualization**

Computer Vision: understand what is in an image

- Pixels  $\rightarrow$  Message or Decision potentially leading to automated actions
- Visualization: create images/video to communicate a message
  - Message  $\rightarrow$  Pixels

# Typical Vision Pipeline on 2D Input



# Typical Vision Pipeline on 3D Input



## **Typical Visualization Pipeline**





#### Moving Towards Autonomous Driving





#### Levels of Automated driving, security requirements



Time

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#### **Automated Vehicle Control**



### Neural Networks



#### **Top-5 Accuracy Image Classification**

Image-Net Large-Scale Visual Recognition Challenge (ILSVRC\*)



\* http://image-net.org/challenges/LSVRC/ \*\*<u>http://www.slideshare.net/NVIDIA/nvidia-ces-2016-press-conference</u>, pg 10 \*\*\* Russakovsky, et al 2014, http://arxiv.org/pdf/1409.0575.pdf



#### **Top-5 Accuracy Image Classification**

Image-Net Large-Scale Visual Recognition Challenge (ILSVRC\*)



\*\*\* Russakovsky, et al 2014, http://arxiv.org/pdf/1409.0575.pdf

#### **CNNs** Explained



Conclusion: We can recognize what we have trained for -> Database of Images



#### **Compute and Memory Requirements**



**Operational Intensity CNN** Memory (SP) Operations for ImageNet datasets [**MB**] [MOPS] [OPS:B] AlexNet – convolutions only 9.3 1332 143 1456 5.97 AlexNet – complete 244 **VGG-16** 552 30823 55.84 55.24 GoogleNet 27.2 1502

CNNs are highly compute and highly memory intensive

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## Binary and Almost Binary Networks Accuracy (published & reproduced results)

Dataset	FP32	BNN	Source
MNIST	99%	99%	[1]
CIFAR-10	92%	90%	[1]
ImageNet (GoogleNet arch)	90% top-5	86% top-5	[2] binary weights
ImageNet (DoReFaNet)	56% top-1	50% top-1	[4] 2-bit activations

[1] Courbariaux, Matthieu, and Yoshua Bengio. "BinaryNet: Training deep neural networks with weights and activations constrained to+ 1 or-1." arXiv preprint arXiv:1602.02830 (2016).

[2] Rastegari, Mohammad, et al. "XNOR-Net: ImageNet Classification Using Binary Convolutional Neural Networks." arXiv preprint arXiv:1603.05279 (2016).

[3] Xundong Wu: High Performance Binarized Neural Networks trained on the ImageNet Classification Task" arXiv:1604.03058

[4] S. Zhou, z.Ni, X. Zhou, H.Wen, Y.Wu, Y. Zou: "DoReFa-Net: Training Low Bitwidth Convolutional Neural Networks with Low Bitwidth Gradients", http://arxiv.org/abs/1606.06160#



## **Emerging: Low-Precision Networks**

>Reducing precision is shown today to work to 6b

- 50x reduction in model size (no external memory needed) [1]
- Reducing to the extreme: binary neural networks (BNNs)



[1] Iandola et al. "SqueezeNet: AlexNet-level accuracy with 50x fewer parameters and< 1MB model size." (2016).

 [2] Sung et al., "Resiliency of Deep Neural Networks Under Quantization", ICLR'16 (fully connected network layers for phoneme recognition)
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MPSoC 2016, K. Vissers

## Roofline model



#### Xilinx Kintex<sup>®</sup> UltraScale<sup>™</sup> KU115

- > 5520 DSP Cores, 663 KLuts
- > 2Tops or more, 16 bit
- > 4 GB, 26Gbyte/sec bandwidth
- Single Slot PCIe, Low Profile
- ► Total card power ~ 40W



AlphaData ADM-PCIE-8K5



## Roofline model for KU115 (ADM-PCIE-8K5) & CNNs



First prototype in Xilinx labs Dublin\* shows 4.8TOPS/sec, 1Mfps for MNIST

\*Yaman Umuroglu (NTNU, Xilinx); Nicholas Fraser (University of Sydney, Xilinx); Michaela Blott (Xilinx Research)

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#### How to reach peak performance

- Use minimal resources, i.e 1DSP per 16 bit Multiply-Accumulate (MAC).
- Use a reduced number of coefficients net (move to the right), e.g. Squeeze net
- > Use the bit-accuracy that makes sense: e.g. 16bit, 8bit, 1 bit
- Use local buffering to avoid spending energy in memory interface or hitting memory bandwidth limitations
- Peak performance in Tops range possible today
- Best in class performance/watt of programmable devices (~10x lower Gops/W for 16bit operation compared to GPUs)

# **Energy and Si area of Computation**



Energy numbers are from Mark Horowitz "Computing's Energy Problem (and what we can do about it)", ISSCC 2014 Area numbers are from synthesized result using Design Compiler under TSMC 45nm tech node. FP units used DesignWare Library.

#### Source: William Dally, "High Performance Hardware for Machine Learning"

#### **Energy Considerations**

- Use local on chip buffering to avoid going to External Memory
- Streaming based solutions are very power efficient
- Threading, and Cache misses are designed for Random access programs
- Streaming and explicit (pre)fetching fit the characteristics of Neural Networks, sliding window style processing is possible.

## Lab setup using the MNIST dataset, Zynq chip



#### ZU+ MPSoC-based Multi-Feature Module



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#### Conclusions

- External Memory transfers are 100-200x more energy then a basic operation: Build architectures that minimize external memory transfers, use on chip local storage.
- > Multiple High-resolution cameras and sensors will be deployed in Automotive systems.
- > Complete vision processing includes standard algorithms and Neural Networks.
- > Reduced precision in Neural Networks is a very promising research direction
- > Compute load will be several Tops, in a few Watts for the complete device.
- > What really works in vision processing is active research: build real systems!
- MPSoC devices (ZU3, ZU4, ZU5, ZU7, ZU9, ZU15) will do (Automotive) system vision processing in a few Watts, including Neural Networks.
- A complete programming environments is available, including OS, High-level Synthesis, and SDSoC.

SDS Comp	oC Dev Environment olete Environment for HW and SV	"Original Source" <b>V Design</b>
Feature	Benefit	Pure SW Dev Environment (Eclipse-Based)
Pure SW Dev Environment	<ul> <li>From C/C++ to fully functional AP SoC without any HW code</li> <li>Familiar, Eclipse-based, SW-centric design environment</li> </ul>	System-Level Profiling
System Level Profiling	<ul> <li>PS/PL performance, area, data transfer estimates in minutes</li> <li>Quickly identify optimal total system architecture</li> </ul>	Exploration Single-Click SW-HW Partitioning
Single-Click SW/HW Partitioning	<ul> <li>Quickly explore different system connectivity in C/C++</li> <li>Find data mover and PS-PL interface for optimal dataflow</li> </ul>	System Optimizing Compiler         ARM Code       Connectivity Optimization       Function Acceleration
System Optimizing Compiler	<ul> <li>Automated function acceleration in logic fabric</li> <li>Generates both ARM software and FPGA bitstream</li> <li>Examine throughput, latency and area tradeoffs</li> </ul>	ARM Compiler Vivado TM Design Suite

Programmable Logic

ment

### Zyng UltraScale+ Block Diagram



#### Zynq® UltraScale+™ MPSoCs: EG Devices

		Smarter Control and Vision			Smarter Network							
	Device Name <sup>(1)</sup>	ZU2EG	ZU3EG	ZU4EG	ZU5EG	ZU7EG	ZU6EG	ZU9EG	ZU15EG	ZU11EG	ZU17EG	ZU19EG
Application	Processor Core	Processor Core Quad-core ARM <sup>®</sup> Cortex <sup>™</sup> -A53 MPCore <sup>™</sup> up to 1.5GHz										
Processor Unit	Memory w/ECC	L1 Cache 32KB I / D per core, L2 Cache 1MB, on-chip Memory 256KB										
Real-Time	Processor Core	Dual-core ARM Cortex-R5 MPCore™ up to 600MHz										
Processor Unit	Memory w/ECC	L1 Cache 32KB I / D per core, Tightly Coupled Memory 128KB per core										
E Graphic & Video	Graphics Processing Unit	Mali™-400 MP2 up to 667MHz										
Acceleration	Memory		L2 Cache 64KB									
S Di Evtornal Momory	Dynamic Memory Interface			x32/x	64: DDR4	, LPDDR4	, DDR3, D	DR3L, LP	DDR3 wi	th ECC		
External Memory	Static Memory Interfaces	NAND, 2x Quad-SPI										
0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0	High-Speed Connectivity PCIe <sup>®</sup> Gen2 x4, 2x USB3.0, SATA 3.1, DisplayPort, 4x Tri-mode Gigabit Ethernet											
e connectivity	General Connectivity	General Connectivity 2xUSB 2.0, 2x SD/SDIO, 2x UART, 2x CAN 2.0B, 2x I2C, 2x SPI, 4x 32b GPIO										
	Power Management	Full / Low / PL / Battery Power Domains										
Integrated Block	Security	RSA, AES, and SHA										
Functionality	AMS - System Monitor	10-bit, 1MSPS - Temperature, Voltage, and Current Monitor										
PS to PL Interface	12 x 32/64/128b AXI Ports											
Drogrammable	System Logic Cells (K)	103	154	192	256	504	469	600	747	653	926	1,143
Functionality	CLB Flip-Flops (K)	94	141	176	234	461	429	548	682	597	847	1,045
	CLB LUTs (K)	47	71	88	117	230	215	274	341	299	423	523
L L	Max. Distributed RAM (Mb)	1.2	1.8	2.6	3.5	6.2	6.9	8.8	11.3	9.1	8.0	9.8
.e Memory	Total Block RAM (Mb)	5.3	7.6	4.5	5.1	11.0	25.1	32.1	26.2	21.1	28.0	34.6
Log	UltraRAM (Mb)	-	-	14.0	18.0	27.0	-	-	31.5	22.5	28.7	36.0
e Clocking	Clock Management Tiles (CMTs)	3	3	4	4	8	4	4	4	8	11	11
Integrated IP	DSP Slices	240	360	728	1,056	1,728	1,973	2,520	3,528	2,928	1,590	1,968
	PCI Express <sup>®</sup> Gen 3x16 / Gen4x8	-	-	2	2	2	-	-	-	4	4	5
	150G Interlaken	-	-	-	-	-	-	-	-	2	2	4
	100G Ethernet MAC/PCS w/RS-FEC	-	-	-	-	-	-	-	-	1	2	4
	AMS - System Monitor	1	1	1	1	1	1	1	1	1	1	1
Speed Grades	Extended <sup>(2)</sup>			-1 -2L -3					-1 -2	2L -3		
	Industrial			-1 -1L -2					-1 -1	L -2		

Notes

1. For full part number details, see the Ordering Information section in DS891, Zyng UltraScale+ MPSoC Overview.

2.-2LE (Tj = 0°C to 110°C). For more details, see the Ordering Information section in DS891, Zyng UltraScale+ MPSoC Overview.

#### Zynq® UltraScale+™ MPSoCs: EV Devices

	Smarter Vision						
	Device Name <sup>(1)</sup>	ZU4EV	ZU5EV	ZU7EV			
Application	Processor Core	Quad-core ARM <sup>®</sup> Cortex <sup>™</sup> -A53 MPCore <sup>™</sup> up to 1.5GHz					
Processor Unit	Memory w/ECC	L1 Cache 32KB I	L1 Cache 32KB I / D per core, L2 Cache 1MB, on-chip Memory 256KB				
Real-Time	Processor Core	Dual-co	Dual-core ARM Cortex-R5 MPCore™ up to 600MHz				
Processor Unit	Memory w/ECC	L1 Cache 32KB I / D per core, Tightly Coupled Memory 128KB per core					
E Graphic & Video	Graphics Processing Unit	Mali™-400 MP2 up to 667MHz					
Acceleration	Memory	L2 Cache 64KB					
S DEvtornal Momory	Dynamic Memory Interface	x32/x64: D	x32/x64: DDR4, LPDDR4, DDR3, DDR3L, LPDDR3 with ECC				
External Wentory	Static Memory Interfaces		NAND, 2x Quad-SPI				
Se Connoctivity	High-Speed Connectivity	PCle <sup>®</sup> Gen2 x4, 2x US	PCIe <sup>®</sup> Gen2 x4, 2x USB3.0, SATA 3.1, DisplayPort, 4x Tri-mode Gigabit Ethernet				
Connectivity	General Connectivity	2xUSB 2.0, 2x SD/SE	2xUSB 2.0, 2x SD/SDIO, 2x UART, 2x CAN 2.0B, 2x I2C, 2x SPI, 4x 32b GPIO				
L Integrated Block	Power Management	Fu	Full / Low / PL / Battery Power Domains				
Functionality	Security		RSA, AES, and SHA				
Functionality	AMS - System Monitor	10-bit, 1MS	10-bit, 1MSPS - Temperature, Voltage, and Current Monitor				
PS to PL Interface	12 x 32/64/128b AXI Ports						
Programmable	System Logic Cells (K)	192	256	504			
	CLB Flip-Flops (K)	176	234	461			
runctionality	CLB LUTs (K)	88	117	230			
<b>a</b>	Max. Distributed RAM (Mb)	2.6	3.5	6.2			
Memory	Total Block RAM (Mb)	4.5	5.1	11.0			
ogio	UltraRAM (Mb)	14.0	18.0	27.0			
Clocking	Clock Management Tiles (CMTs)	4	4	8			
abl	DSP Slices	728	1,056	1,728			
Integrated IP	Video Codec Unit (VCU)	1	1	1			
	PCI Express <sup>®</sup> Gen 3x16 / Gen4x8	2	2	2			
	150G Interlaken	-	-	-			
	100G Ethernet MAC/PCS w/RS-FEC	-	-	-			
	AMS - System Monitor	1	1	1			
Speed Grades	Extended <sup>(2)</sup>		-1 -2L -3				
Spece Grades	Industrial		-1 -1L -2				

Notes:

1. For full part number details, see the Ordering Information section in <u>DS891</u>, *Zynq UltraScale+ MPSoC Overview*.

2.-2LE (Tj = 0°C to 110°C). For more details, see the Ordering Information section in DS891, Zynq UltraScale+ MPSoC Overview.

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